

Supply Voltage 0.9 to 3.6 V

- One-Cell Mode supports 0.9 to 1.8 V operation
- Two-Cell Mode supports 1.8 to 3.6 V operation
- Built-in dc-dc converter with 1.8 to 3.3 V output for use in one-cell mode
- Built-in LDO regulator allows a high analog supply voltage and low digital core voltage
- 2 built-in supply monitors (brownout detectors)

10-Bit Analog to Digital Converter

- 1LSB INL; no missing codes
- Programmable throughput up to 300 ksps
- 23 external inputs
- On-Chip Voltage Reference
- On-Chip PGA allows measuring voltages up to twice the reference voltage
- 16-bit Auto-Averaging Accumulator with Burst Mode provides increased ADC resolution
- Data dependent windowed interrupt generator
- Built-in temperature sensor

Two Comparators

- Programmable hysteresis and response time
- Configurable as wake-up or reset source
- 23 Capacitive Touch Sense inputs

6-Bit Programmable Current Reference

- Up to $\pm 500 \mu\text{A}$. Can be used as a bias or for generating a custom reference voltage

On-Chip Debug

- On-chip debug circuitry facilitates full-speed, non-intrusive in-system debug (no emulator required)
- Provides breakpoints, single stepping
- Inspect/modify memory and registers
- Complete development kit

High-Speed 8051 μC Core

- Pipelined instruction architecture; executes 70% of instructions in 1 to 2 system clocks
- 25 MIPS throughput with 25 MHz clock
- Expanded interrupt handler

Memory

- 4352 bytes internal data RAM (256+4096)
- 64 kB Flash; In-system programmable in 1024-byte sectors--1024 bytes are reserved in the 64 kB devices

Digital Peripherals

- 24 port I/O; All 5 V tolerant with high sink current and programmable drive strength
- Hardware SMBus™ (I²C Compatible), 2 x SPI™, and UART serial ports available concurrently
- Four general purpose 16-bit counter/timer array with six capture/compare modules and watchdog timer
- Hardware SmarTClock operates down to 0.9V and requires less than 0.5 μA supply current

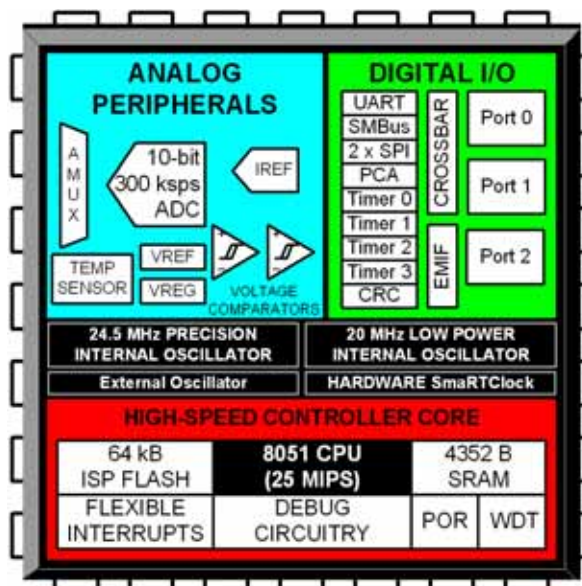
Clock Sources

- Internal oscillators: 24.5 MHz, 2% accuracy supports UART operation; 20 MHz low power oscillator requires very little bias current
- External oscillator: Crystal, RC, C, or CMOS Clock
- SmarT Clock oscillator: 32 kHz Crystal or internal self-oscillate mode
- Can switch between clock sources on-the-fly; useful in implementing various power saving modes

Temperature range: –40 to +85 °C

Full Technical Data Sheet

- C8051F93x-C8051F92x



C8051F930-G1DI

1. Ordering Information

Table 1.1. Product Selection Guide¹

Ordering Part Number	MIPS (Peak)	Flash Memory (kB)	RAM (Bytes)	SmArTClock Real Time Clock	SMBus/I ² C	UART	Enhanced SPI	Timers (16-bit)	Programmable Counter Array	Digital Port I/Os	10-bit 300ksps ADC	Programmable Current Reference	Internal Voltage Reference	Temperature Sensor	Analog Comparators	Lead-free (RoHS Compliant)	Wafer Thickness
C8051F930-G-G1DI	25	64	4352	✓	1	1	2	4	✓	24	✓	✓	✓	✓	2	✓	28.54 mil / 725 µm (no back- grind)
C8051F930-G-GDI ²	25	64	4352	✓	1	1	2	4	✓	24	✓	✓	✓	✓	2	✓	12 mil (backgrind)

Notes:

- 1024 bytes reserved for factory use.
- C8051F930-G-GDI is obsolete.

2. Pin Definitions

Table 2.1. Pin Definitions for the C8051F930-GDI

Name	Physical Pad Number	Type	Description
VBAT	6	P In	Battery Supply Voltage. Must be 0.9 to 1.8 V in single-cell battery mode and 1.8 to 3.6 V in dual-cell battery mode.
V _{DD} / DC+	4	P In P Out	Power Supply Voltage. Must be 1.8 to 3.6 V. This supply voltage is not required in low power sleep mode. This voltage must always be ≥ VBAT. Positive output of the dc-dc converter. In single-cell battery mode, a 1uF ceramic capacitor is required between DC+ and DC-. This pin can supply power to external devices when operating in single-cell battery mode.
DC- / GND	2	P In G	DC-DC converter return current path. In single-cell battery mode, this pin is typically not connected to ground. In dual-cell battery mode, this pin must be connected directly to ground.
GND	3	G	Required Ground.
DCEN	5	P In G	DC-DC Enable Pin. In single-cell battery mode, this pin must be connected to VBAT through a 0.68 μH inductor. In dual-cell battery mode, this pin must be connected directly to ground.
RST / C2CK	7	D I/O D I/O	Device Reset. Open-drain output of internal POR or V _{DD} monitor. An external source can initiate a system reset by driving this pin low for at least 15 μs. A 1 kΩ to 5 kΩ pullup to V _{DD} is recommended. See Reset Sources section of the C8051F93x-C8051F92x data sheet for a complete description. Clock signal for the C2 Debug Interface.
P2.7 / C2D	8	D I/O D I/O	Port 2.7. This pin can only be used as GPIO. The Crossbar cannot route signals to this pin and it cannot be configured as an analog input. See Port I/O section the C8051F93x-C8051F92x data sheet for a complete description. Bi-directional data signal for the C2 Debug Interface.
XTAL3	11	A In	SmaRTClock Oscillator Crystal Input.
XTAL4	10	A Out	SmaRTClock Oscillator Crystal Output.

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Table 2.1. Pin Definitions for the C8051F930-GDI (Continued)

Name	Physical Pad Number	Type	Description
P0.0	39	D I/O or A In	Port 0.0. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description.
V _{REF}		A In A Out	External V _{REF} Input. Internal V _{REF} Output. External V _{REF} decoupling capacitors are recommended. See ADC0 section of the C8051F93x-C8051F92x data sheet for details.
P0.1	38	D I/O or A In	Port 0.1. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description.
AGND		G	Optional Analog Ground. See ADC0 section of the C8051F93x-C8051F92x data sheet for details.
P0.2	33	D I/O or A In	Port 0.2. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description.
XTAL1		A In	External Clock Input. This pin is the external oscillator return for a crystal or resonator. See Oscillator section of the C8051F93x-C8051F92x data sheet for a complete description.
P0.3	32	D I/O or A In	Port 0.3. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description.
XTAL2		A Out D In A In	External Clock Output. This pin is the excitation driver for an external crystal or resonator. External Clock Input. This pin is the external clock input in external CMOS clock mode. External Clock Input. This pin is the external clock input in capacitor or RC oscillator configurations. See Oscillator section of the C8051F93x-C8051F92x data sheet for complete details.
P0.4	31	D I/O or A In	Port 0.4. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description.
TX		D Out	UART TX Pin. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description.

Table 2.1. Pin Definitions for the C8051F930-GDI (Continued)

Name	Physical Pad Number	Type	Description
P0.5 RX	30	D I/O or A In D In	Port 0.5. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description. UART RX Pin. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description.
P0.6 CNVSTR	29	D I/O or A In D In	Port 0.6. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description. External Convert Start Input for ADC0. See ADC0 section of the C8051F93x-C8051F92x data sheet for a complete description.
P0.7 IREF0	28	D I/O or A In A Out	Port 0.7. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description. IREF0 Output. See IREF section of the C8051F93x-C8051F92x data sheet for complete description.
P1.0 AD0	27	D I/O or A In D I/O	Port 1.0. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description. May also be used as SCK for SPI1. Address/Data 0.
P1.1 AD1	26	D I/O or A In D I/O	Port 1.1. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description. May also be used as MISO for SPI1. Address/Data 1.
P1.2 AD2	25	D I/O or A In D I/O	Port 1.2. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description. May also be used as MOSI for SPI1. Address/Data 2.
P1.3 AD3	24	D I/O or A In D I/O	Port 1.3. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description. May also be used as NSS for SPI1. Address/Data 3.
P1.4 AD4	21	D I/O or A In D I/O	Port 1.4. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description. Address/Data 4.

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Table 2.1. Pin Definitions for the C8051F930-GDI (Continued)

Name	Physical Pad Number	Type	Description
P1.5	20	D I/O or A In	Port 1.5. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description.
AD5		D I/O	Address/Data 5.
P1.6	19	D I/O or A In	Port 1.6. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description.
AD6		D I/O	Address/Data 6.
P1.7	18	D I/O or A In	Port 1.7. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description.
AD7		D I/O	Address/Data 7.
P2.0	17	D I/O or A In	Port 2.0. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description.
AD8		D I/O	Address/Data 8.
P2.1	16	D I/O or A In	Port 2.1. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description.
AD9		D I/O	Address/Data 9.
P2.2	15	D I/O or A In	Port 2.2. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description.
AD10		D I/O	Address/Data 10.
P2.3	14	D I/O or A In	Port 2.3. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description.
AD11		D I/O	Address/Data 11.
P2.4	13	D I/O or A In	Port 2.4. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description.
ALE		D O	Address Latch Enable.

Table 2.1. Pin Definitions for the C8051F930-GDI (Continued)

Name	Physical Pad Number	Type	Description
P2.5 \overline{RD}	12	D I/O or A In D O	Port 2.5. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description. Read Strobe.
P2.6 \overline{WR}	9	D I/O or A In D O	Port 2.6. See Port I/O section of the C8051F93x-C8051F92x data sheet for a complete description. Write Strobe.

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3. Bonding Instructions

Table 3.1. Bond Pad Coordinates (Relative to Center of Die)

Table 3.2. Physical Pad Number	Table 3.3. Example Package Pin Number (QFN-32)	Table 3.4. Package Pin Name	Table 3.5. Physical Pad X (μm)	Table 3.6. Physical Pad Y (μm)
Table 3.7. 1	Reserved*	—	-1013	614
Table 3.8. 2	1	DC-/GND	-1013	494
Table 3.9. 3	2	GND	-1013	247
Table 3.10. 4	3	VDD/DC+	-1013	92
Table 3.11. 5	4	DCEN	-1013	-91
Table 3.12. 6	5	VBAT	-1013	-315
Table 3.13. 7	6	$\overline{\text{RST}}/\text{C2CK}$	-1013	-626
Table 3.14. 8	7	P2.7/C2D	-1013	-810
Table 3.15. 9	8	P2.6/WR	-810	-1013
Table 3.16. 10	9	XTAL4	-525	-1013
Table 3.17. 11	10	XTAL3	-303	-1013
Table 3.18. 12	11	P2.5/RD	-54	-1013
Table 3.19. 13	12	P2.4/ALE	130	-1013
Table 3.20. 14	13	P2.3/AD11	286	-1013
Table 3.21. 15	14	P2.2/AD10	470	-1013
Table 3.22. 16	15	P2.1/AD9	626	-1013
Table 3.23. 17	16	P2.0/AD8	810	-1013
Table 3.24. 18	17	P1.7/AD7	1013	-810
Table 3.25. 19	18	P1.6/AD6	1013	-626
Table 3.26. 20	19	P1.5/AD5	1013	-470
Table 3.27. 21	20	P1.4/AD4	1013	-286
Table 3.28. 22	Reserved*	—	1013	-174
Table 3.29. 23	Reserved*	—	1014	-94
Table 3.30. 24	21	P1.3/AD3	1013	137

*Note: Pins marked "Reserved" should not be connected.

Table 3.1. Bond Pad Coordinates (Relative to Center of Die) (Continued)

Table 3.2. Physical Pad Number	Table 3.3. Example Package Pin Number (QFN-32)	Table 3.4. Package Pin Name	Table 3.5. Physical Pad X (μm)	Table 3.6. Physical Pad Y (μm)
Table 3.31. 25	22	P1.2/AD2	1013	279
Table 3.32. 26	23	P1.1/AD1	1013	477
Table 3.33. 27	24	P1.0/AD0	1013	619
Table 3.34. 28	25	P0.7/IREF0	1013	817
Table 3.35. 29	26	P0.6/CNVSTR	817	1013
Table 3.36. 30	27	P0.5/RX	619	1013
Table 3.37. 31	28	P0.4/TX	477	1013
Table 3.38. 32	29	P0.3/XTAL2	279	1013
Table 3.39. 33	30	P0.2/XTAL1	137	1013
Table 3.40. 34	Reserved*	—	-7	1013
Table 3.41. 35	Reserved*	—	-97	1013
Table 3.42. 36	Reserved*	—	-413	1013
Table 3.43. 37	Reserved*	—	-503	1013
Table 3.44. 38	31	P0.1/AGND	-626	1013
Table 3.45. 39	32	P0.0/VREF	-810	1013

***Note:** Pins marked “Reserved” should not be connected.

C8051F930-G1DI

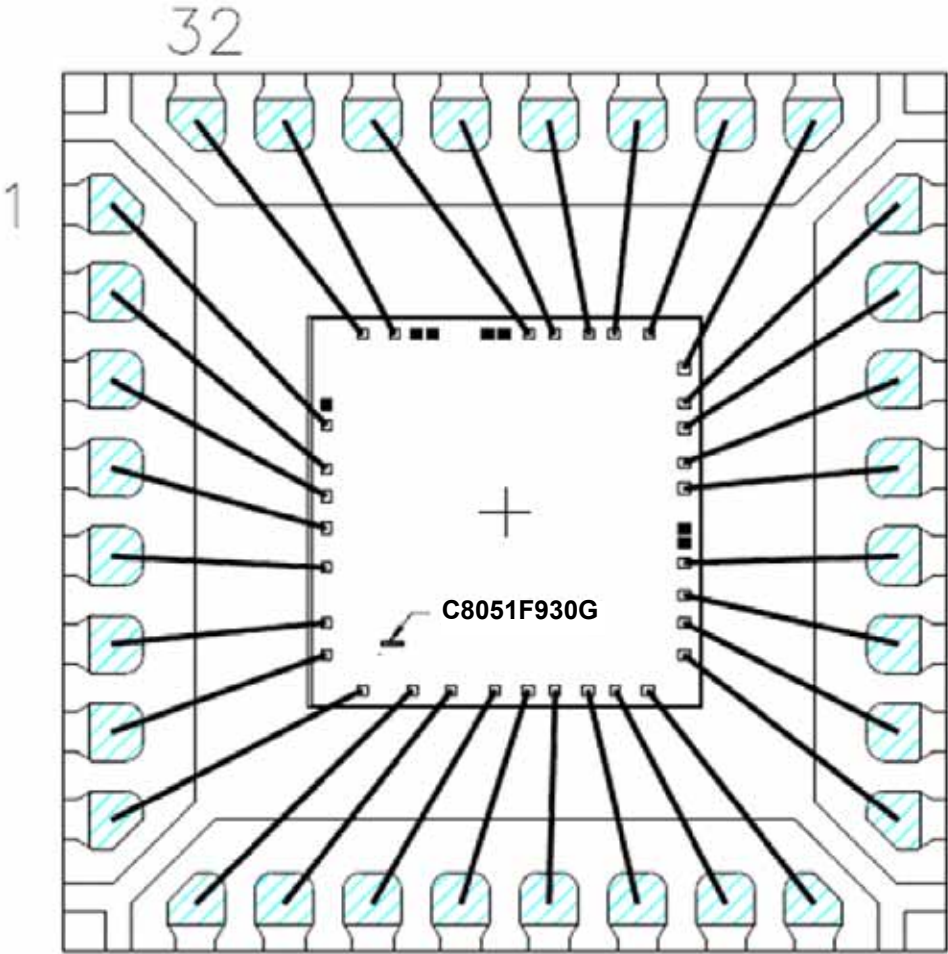


Figure 3.1. Example Die Bonding (QFN-32)

Table 3.46. Wafer and Die Information

Wafer ID	C8051F930G
Wafer Dimensions	8 in
Die Dimensions	2.28 mm x 2.28 mm
Wafer Thickness (with backgrind)	12 mil ±1 mil
Wafer Thickness (no backgrind)	28.54 mil ±1 mil, 725 µm
Wafer Identification	Notch
Scribe Line Width	80 µm
Die Per Wafer*	Contact Sales for info
Passivation	Standard
Wafer Packaging Detail	Wafer Jar
Bond Pad Dimensions	60 µm x 60 µm
Maximum Processing Temperature	250 °C
Electronic Die Map Format	.txt
Bond Pad Pitch Minimum	142 µm
*Note: This is the Expected Known Good Die yielded per wafer and represents the batch order quantity (one wafer).	

C8051F930-G1DI

4. Wafer Storage Guidelines

It is necessary to conform to appropriate wafer storage practices to avoid product degradation or contamination.

- Wafers may be stored for up to 18 months in the original packaging supplied by Silicon Labs.
- Wafers must be stored at a temperature of 18–24 °C.
- Wafers must be stored in a humidity-controlled environment with a relative humidity of <30%.
- Wafers should be stored in a clean, dry, inert atmosphere (e.g. nitrogen or clean, dry air).

5. Failure Analysis (FA) Guidelines

Certain conditions must be met for Silicon Laboratories to perform Failure Analysis on devices sold in wafer form.

- In order to conduct failure analysis on a device in a customer-provided package, Silicon Laboratories must be provided with die assembled in an industry standard package that is pin compatible with existing packages Silicon Laboratories offers for the device. Initial response time for FA requests that meet this requirements will follow the standard FA guidelines for packaged parts.
- If retest of the entire wafer is requested, Silicon Laboratories must be provided with the whole wafer. Silicon Laboratories cannot retest any wafers that have been sawed, diced, backgrind or are on tape. Initial response time for FA requests that meet this requirements will be three weeks.

C8051F930-G1DI

DOCUMENT CHANGE LIST

Revision 1.1 to Revision 1.2

- Changed Wafer Packaging Detail to “Wafer Jar” in Table 3.46 on page 11.

Revision 1.2 to Revision 1.3

- Replaced “C8051F930-GDI” with “C8051F930-G-GDI” (except in title).
- Updated Table 1.1 on page 2 with C8051F930-G-G1DI row.
- Updated label on Figure 3.1 on page 10 to “C8051F930G”.
- Updated Table 3.46 on page 11.
- Added “Failure Analysis (FA) Guidelines” on page 13.

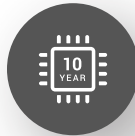
Revision 1.3 to Revision 1.4

- Data sheet renamed from C8051F930-GDI to C8051F930-G1DI.
- Updated Table 1.1, “Product Selection Guide¹,” on page 2 to add “Obsolete” Note.

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